



GAN080-650EBE

650 V, 80 mOhm Gallium Nitride (GaN) FET in a DFN
8 mm x 8 mm package

5 May 2023

Product data sheet

1. General description

The GAN080-650EBE is a general purpose 650 V, 80 mΩ Gallium Nitride (GaN) FET in a DFN 8 mm x 8 mm surface mount package. It is a normally-off e-mode device offering superior performance.

2. Features and benefits

- Enhancement mode - normally-off power switch
- Ultra high frequency switching capability
- No body diode
- Low gate charge, low output charge
- Qualified for standard applications
- ESD protection
- RoHS, Pb-free, REACH-compliant
- High efficiency and high power density
- Low package inductance and low package resistance

3. Applications

- High power density and high efficiency power conversion
- AC-to-DC converters, totem pole PFC
- DC-to-DC converters
- Fast battery charging, mobile phone, laptop, tablet and USB type-C chargers
- Datacom and telecom (AC-to-DC and DC-to-DC) converters
- Motor drives
- Solar (PV) inverters
- Class D audio amplifiers, TV PSU and LED drivers

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$-55\text{ °C} \leq T_j \leq 150\text{ °C}$	-	-	650	V
V_{TDS}	transient drain to source voltage	pulsed; $t_p = 1\text{ }\mu\text{s}$; $\delta_{factor} = 0.01$	-	-	800	V
I_D	drain current	$V_{GS} = 6\text{ V}$; $T_{mb} = 25\text{ °C}$	[1]	-	29	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1	-	-	240	W
T_j	junction temperature		-55	-	150	°C
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 6\text{ V}$; $I_D = 8\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11 ; Fig. 12 ; Fig. 13	-	60	80	mΩ
		$V_{GS} = 6\text{ V}$; $I_D = 8\text{ A}$; $T_j = 150\text{ °C}$; Fig. 11 ; Fig. 14	-	135	-	mΩ

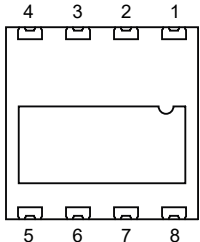
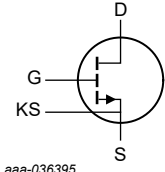
650 V, 80 mOhm Gallium Nitride (GaN) FET in a DFN 8 mm x 8 mm package

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R_G	gate resistance	$f = 5 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$; open drain	-	3	-	Ω
Dynamic characteristics						
Q_{GD}	gate-drain charge	$I_D = 8 \text{ A}$; $V_{DS} = 400 \text{ V}$; $V_{GS} = 6 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 15 ; Fig. 16	-	2.2	-	nC
$Q_{G(\text{tot})}$	total gate charge		-	6.2	-	nC
Q_{oss}	output charge	$V_{GS} = 0 \text{ V}$; $V_{DS} = 400 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	[2]	60	-	nC

- [1] Limited by device saturation
- [2] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain	 <p>Transparent top view</p> <p>DFN8080-8 (SOT8074-1)</p>	 <p>aaa-036395</p>
2	D	drain		
3	D	drain		
4	D	drain		
5	S	source		
6	S	source		
7	KS	kelvin source		
8	G	gate		
mb	S	mounting base; connected to source		

6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
GAN080-650EBE	DFN8080-8	plastic thermal enhanced small outline package; no leads; 8 terminals; body: 8 x 8 x 0.9 mm	SOT8074-1

7. Marking

Table 4. Marking codes

Type number	Marking code
GAN080-650EBE	080IEBE

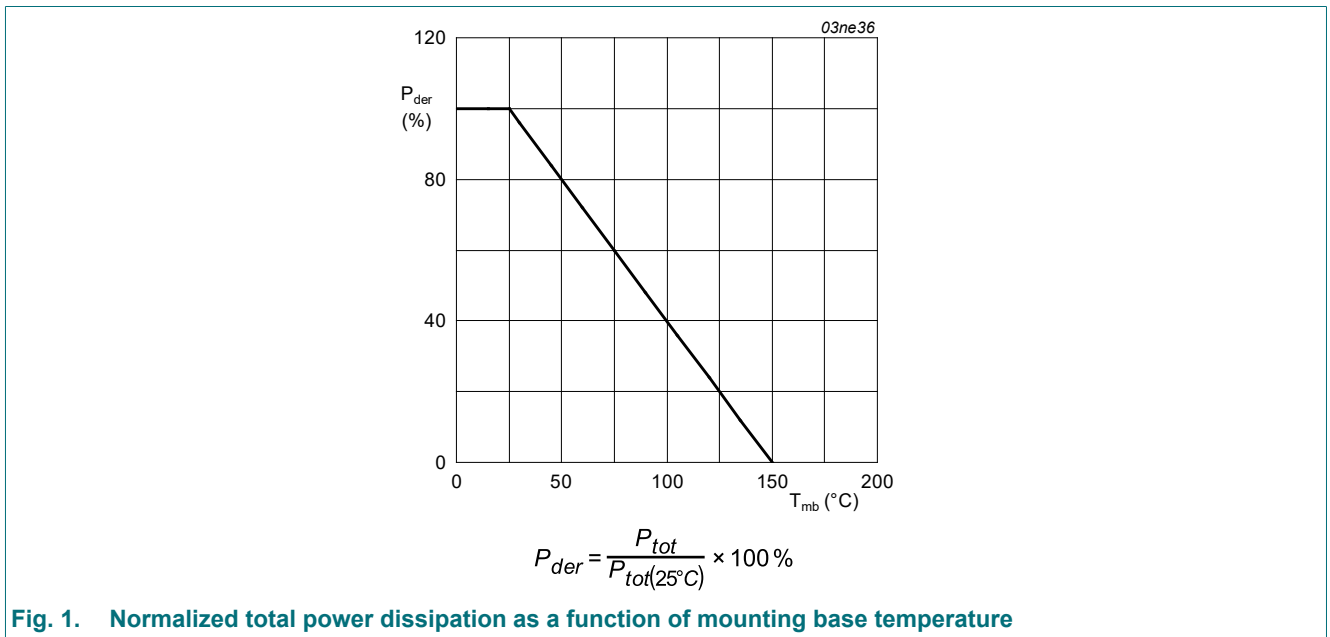
8. Limiting values

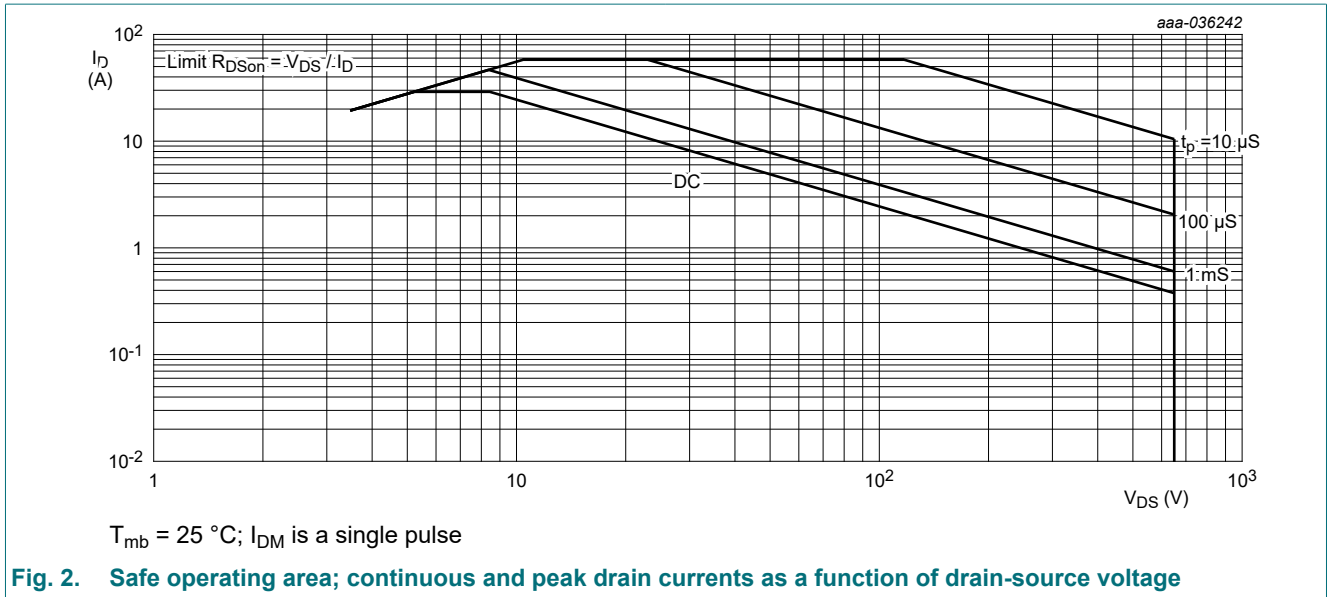
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). $T_j = 25\text{ °C}$ unless otherwise stated.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$-55\text{ °C} \leq T_j \leq 150\text{ °C}$		-	650	V
V_{TDS}	transient drain to source voltage	pulsed; $t_p = 1\text{ }\mu\text{s}$; $\delta_{factor} = 0.01$		-	800	V
V_{GS}	gate-source voltage			-6	7	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1		-	240	W
I_D	drain current	$V_{GS} = 6\text{ V}$; $T_{mb} = 25\text{ °C}$	[1]	-	29	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$; $T_{mb} = 25\text{ °C}$; Fig. 2	[1]	-	58	A
T_{stg}	storage temperature			-55	150	°C
T_j	junction temperature			-55	150	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C

[1] Limited by device saturation

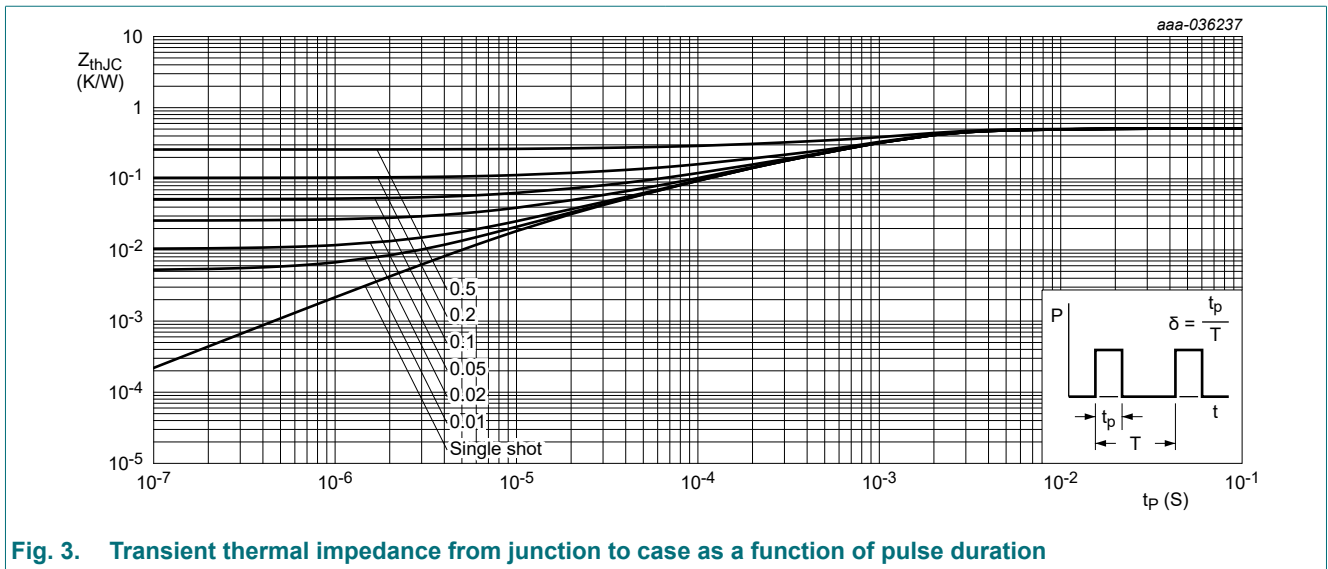




9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	Fig. 3	-	-	0.52	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	-	33.6	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 30.7 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 8	1.2	1.7	2.5	V
		$I_D = 30.7 \text{ mA}$; $V_{DS} = V_{GS}$; $T_j = 150 \text{ }^\circ\text{C}$; Fig. 8	-	1.6	-	V
I_{DSS}	drain leakage current	$V_{DS} = 650 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 9	-	1	65	μA
		$V_{DS} = 650 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$; Fig. 9	-	13	390	μA
I_{GSS}	gate leakage current	$V_{GS} = 6 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 10	-	163	-	μA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 6 \text{ V}$; $I_D = 8 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 11 ; Fig. 12 ; Fig. 13	-	60	80	m Ω
		$V_{GS} = 6 \text{ V}$; $I_D = 8 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$; Fig. 11 ; Fig. 14	-	135	-	m Ω
R_G	gate resistance	$f = 5 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$; open drain	-	3	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 8 \text{ A}$; $V_{DS} = 400 \text{ V}$; $V_{GS} = 6 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 15 ; Fig. 16	-	6.2	-	nC
Q_{GS}	gate-source charge		-	0.5	-	nC
Q_{GD}	gate-drain charge		-	2.2	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 8 \text{ A}$; $V_{DS} = 400 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 15	-	2.2	-	V
C_{iss}	input capacitance	$V_{DS} = 400 \text{ V}$; $V_{GS} = 0 \text{ V}$; $f = 100 \text{ kHz}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 17	-	225	-	pF
C_{oss}	output capacitance		-	70	-	pF
C_{rss}	reverse transfer capacitance		-	0.5	-	pF
$C_{o(er)}$	effective output capacitance, energy related	$0 \text{ V} \leq V_{DS} \leq 400 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 18	[1]	105	-	pF
$C_{o(tr)}$	effective output capacitance, time related	$0 \text{ V} \leq V_{DS} \leq 400 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	[2]	150	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 400 \text{ V}$; $V_{GS} = 6 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; $I_D = 16 \text{ A}$; $L = 318 \text{ } \mu\text{H}$; $R_{on} = 10 \text{ } \Omega$; $R_{off} = 2 \text{ } \Omega$; Fig. 19 ; Fig. 20	-	3	-	ns
t_r	rise time		-	4	-	ns
$t_{d(off)}$	turn-off delay time		-	5	-	ns
t_f	fall time		-	4	-	ns
Q_{oss}	output charge	$V_{GS} = 0 \text{ V}$; $V_{DS} = 400 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$	[3]	60	-	nC
Source-drain characteristics						
V_{SD}	source-drain voltage	$I_S = 8 \text{ A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$; Fig. 21 ; Fig. 22 ; Fig. 23 ; Fig. 24	-	2.3	-	V

[1] $C_{o(er)}$ is the fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400 V

[2] $C_{o(tr)}$ is the fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400 V

[3] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

650 V, 80 mOhm Gallium Nitride (GaN) FET in a DFN 8 mm x 8 mm package

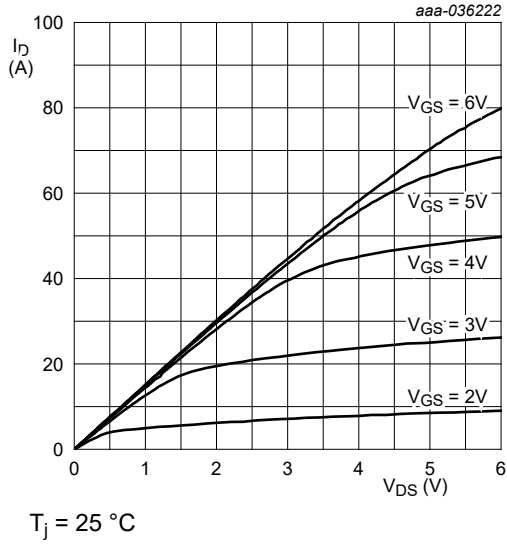


Fig. 4. Output characteristics: drain current as a function of drain-source voltage; typical values

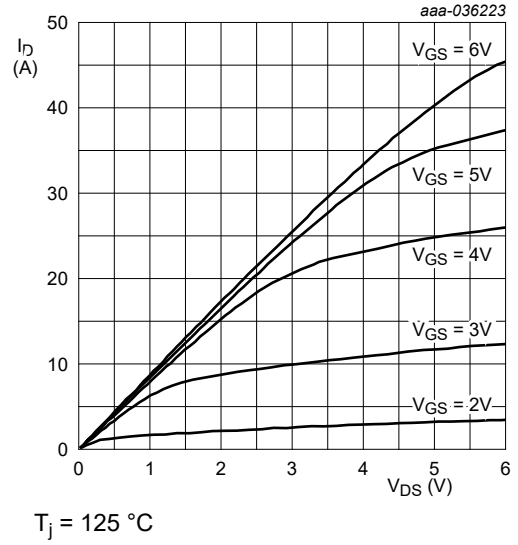


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

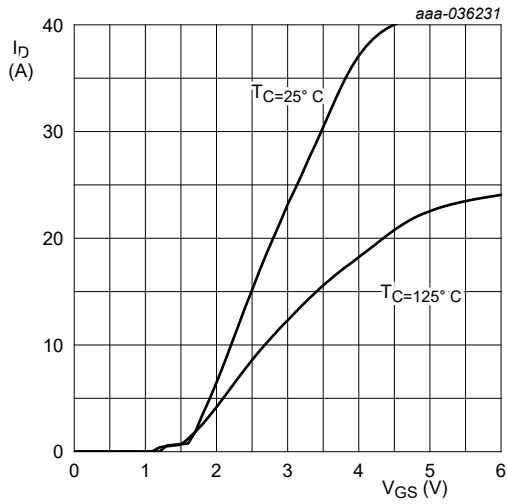


Fig. 6. Transfer characteristics; drain current as a function of gate-source voltage; typical values

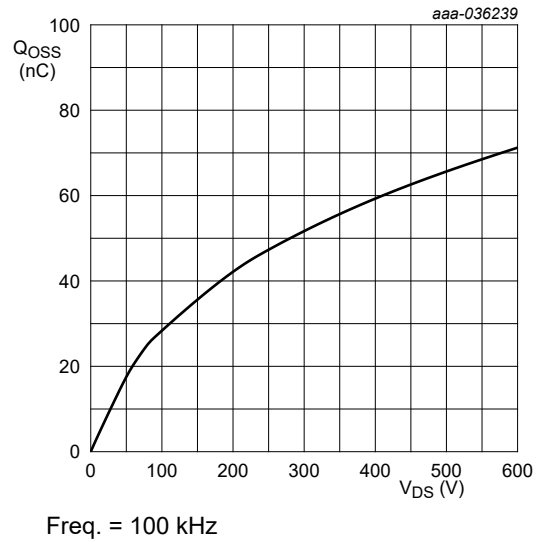
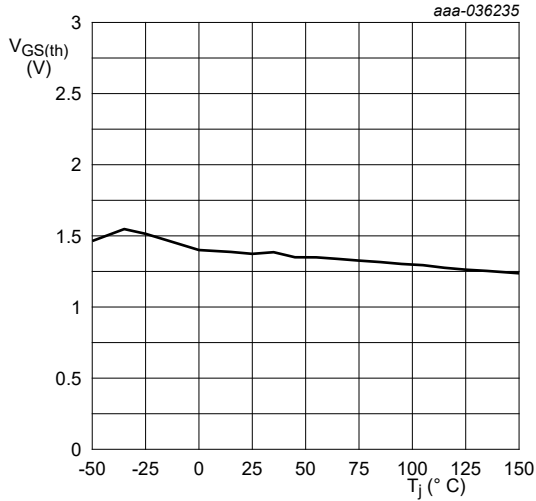
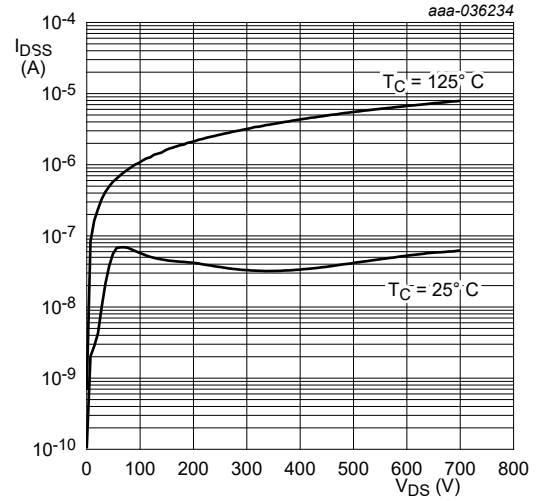


Fig. 7. Output charge as a function of drain-source voltage; typical values
Freq. = 100 kHz



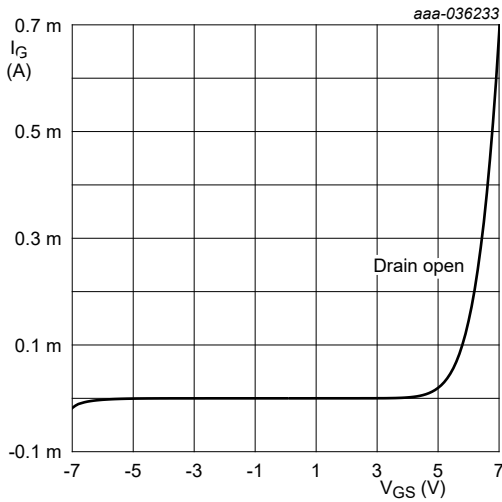
$V_{GS} = V_{DS}$; $I_D = 30.7 \text{ mA}$

Fig. 8. Gate-source threshold voltage as a function of junction temperature



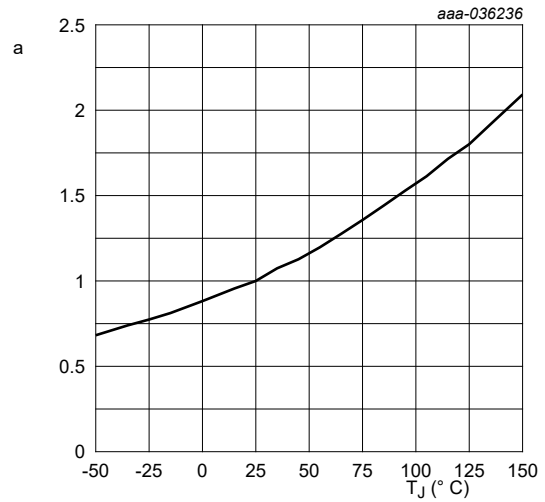
$V_{GS} = 0 \text{ V}$

Fig. 9. Drain-source current as a function of drain-source voltage; typical values



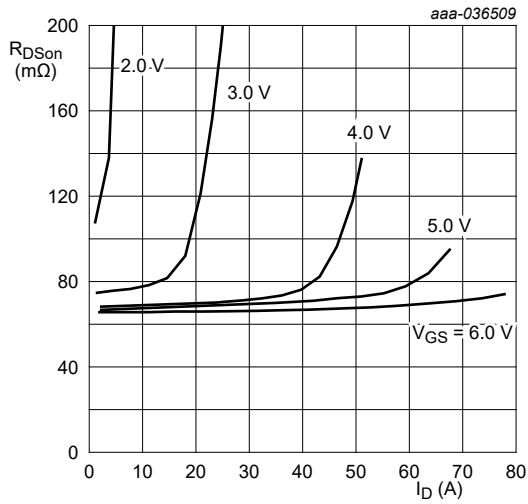
I_g reverse turn on by ESD unit

Fig. 10. Gate-source current as a function of gate-source voltage; typical values



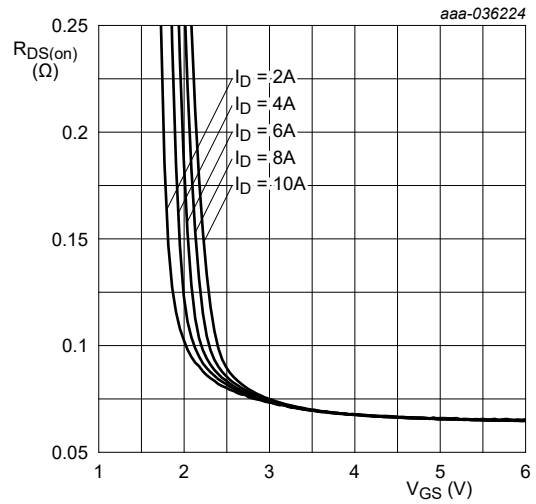
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature



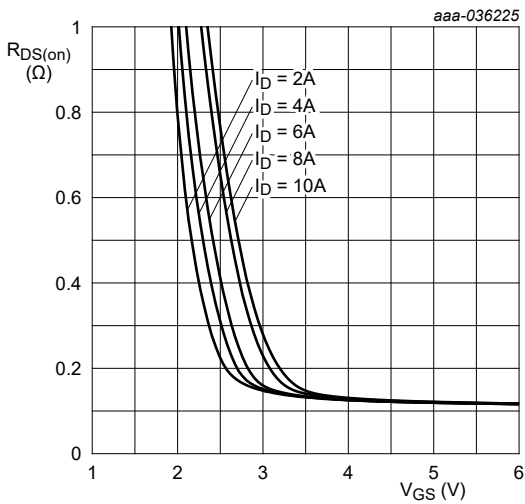
$T_j = 25^\circ\text{C}$

Fig. 12. Drain-source on-state resistance as a function of drain current ; typical values



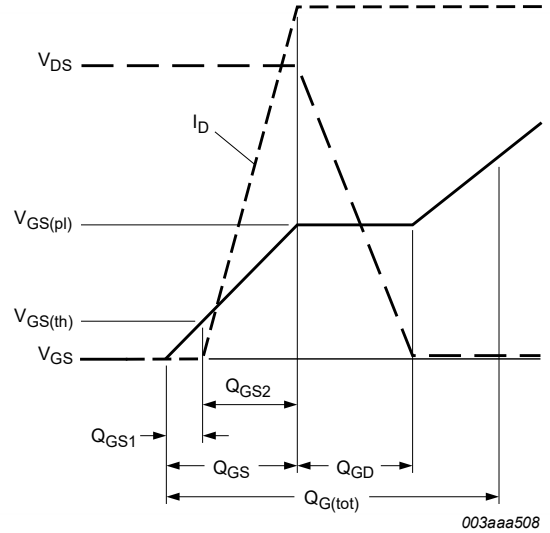
$T_j = 25^\circ\text{C}$

Fig. 13. Drain-source on-state resistance as a function of gate-source voltage; typical values



$T_j = 125^\circ\text{C}$

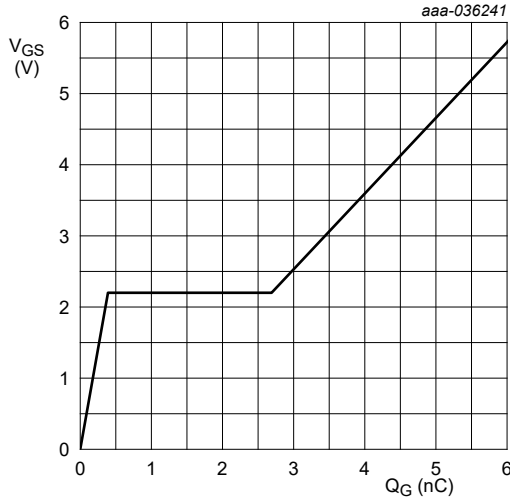
Fig. 14. Drain-source on-state resistance as a function of gate-source voltage; typical values



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Fig. 15. Gate charge waveform definitions

650 V, 80 mOhm Gallium Nitride (GaN) FET in a DFN 8 mm x 8 mm package



$T_J = 25\text{ }^\circ\text{C}$; $I_D = 8\text{ A}$

Fig. 16. Gate-source voltage as a function of gate charge; typical values

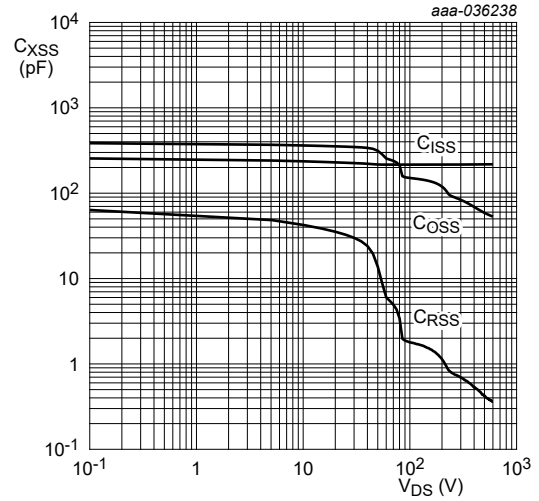
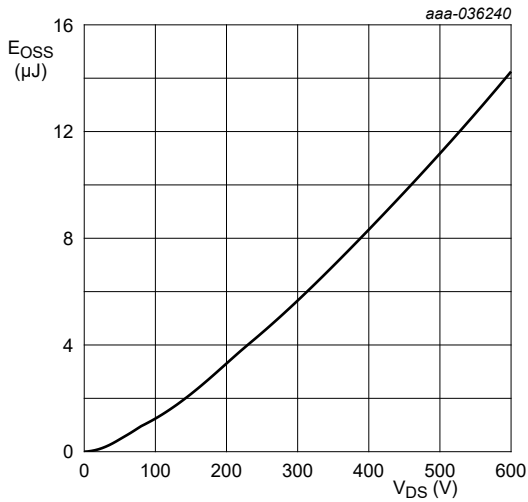
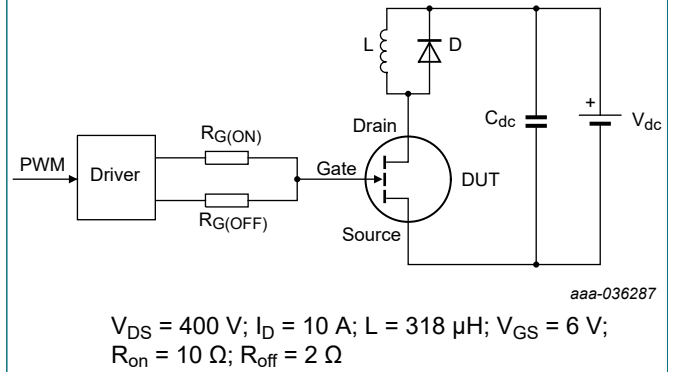


Fig. 17. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



Freq. = 100 kHz

Fig. 18. COSS stored energy as a function of drain-source voltage; typical values



$V_{DS} = 400\text{ V}$; $I_D = 10\text{ A}$; $L = 318\text{ }\mu\text{H}$; $V_{GS} = 6\text{ V}$;
 $R_{on} = 10\text{ }\Omega$; $R_{off} = 2\text{ }\Omega$

Fig. 19. Typical switching times with inductive load

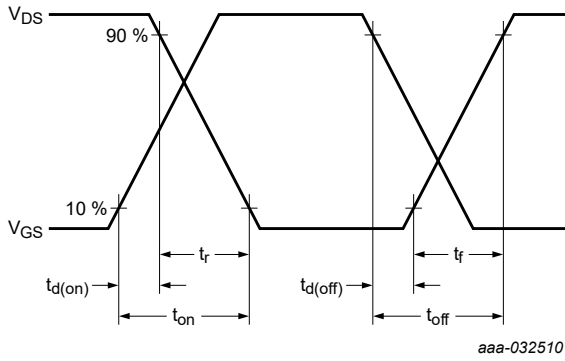
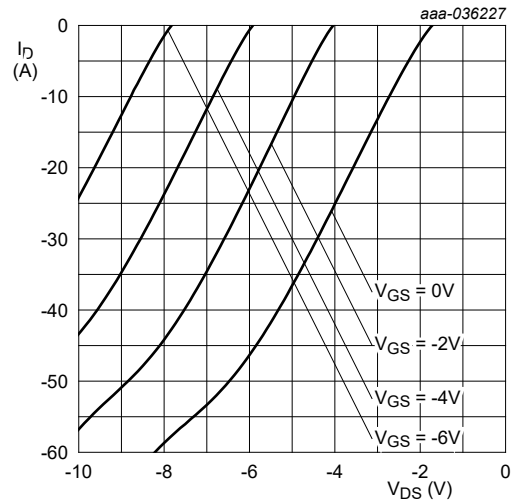
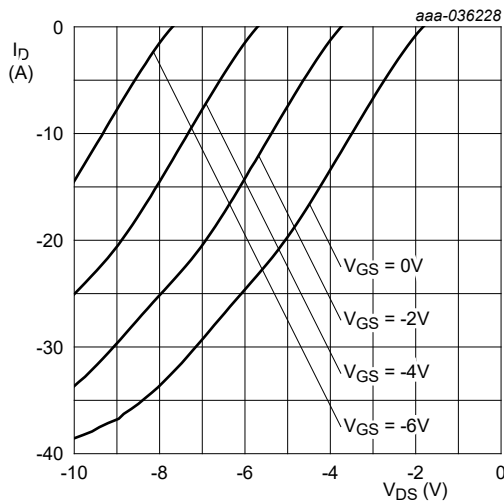


Fig. 20. Switching time waveform



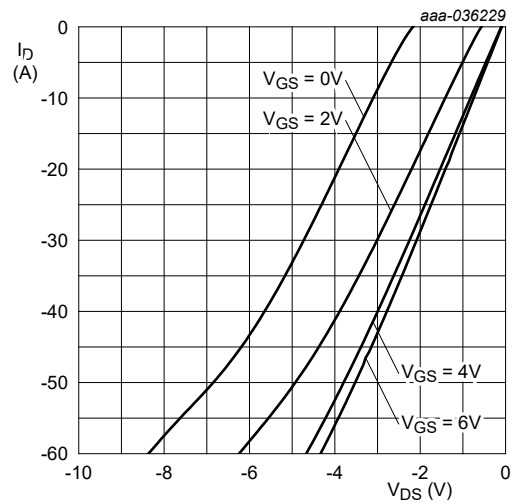
$T_j = 25\text{ }^\circ\text{C}$

Fig. 21. Source current as a function of source-drain voltage; typical values



$T_j = 125\text{ }^\circ\text{C}$

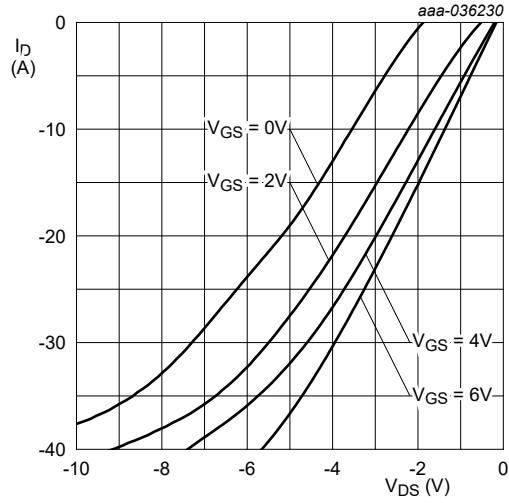
Fig. 22. Source current as a function of source-drain voltage; typical values



$T_j = 25\text{ }^\circ\text{C}$

Fig. 23. Source current as a function of source-drain voltage; typical values

650 V, 80 mOhm Gallium Nitride (GaN) FET in a DFN 8 mm x 8 mm package



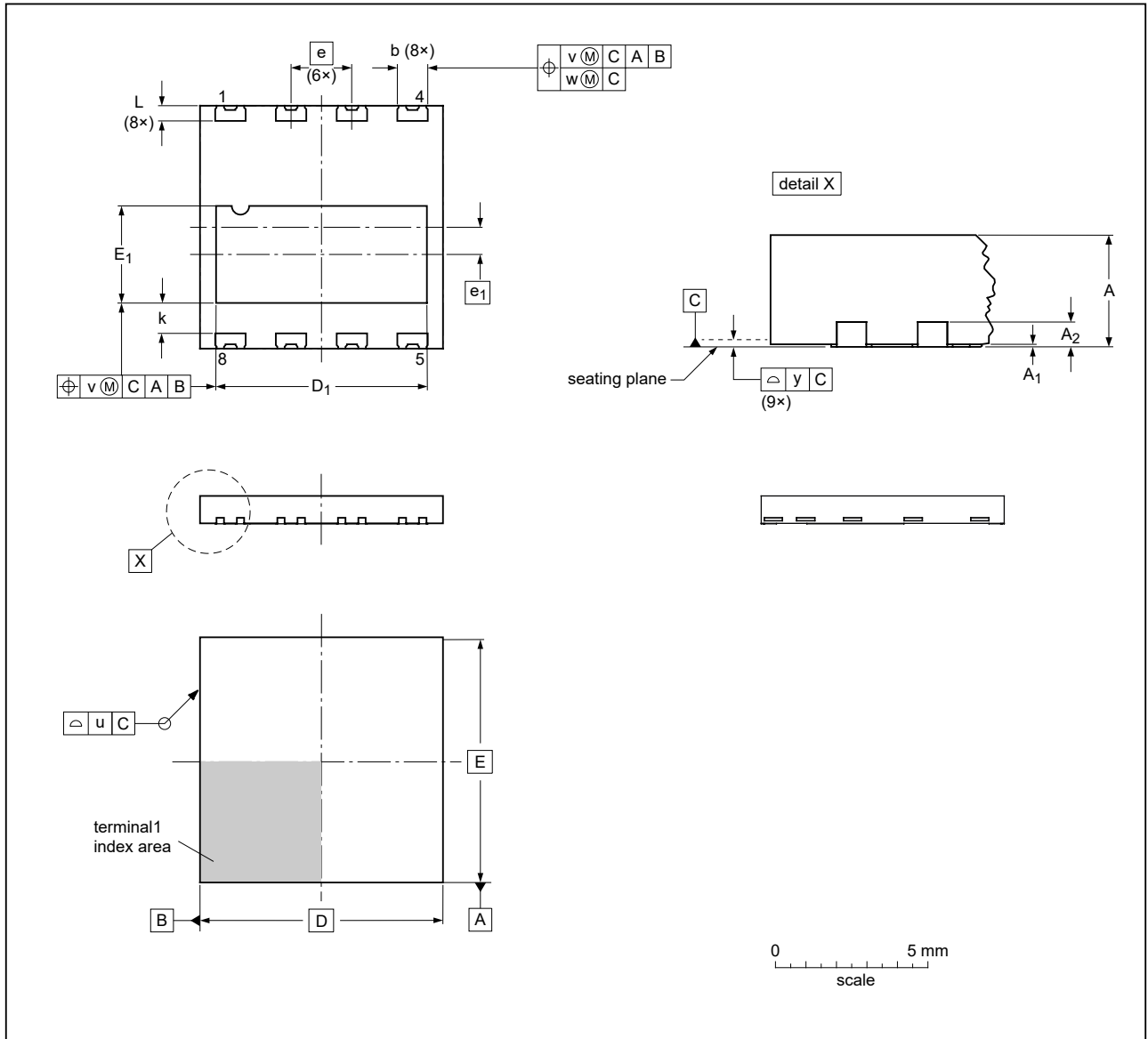
$T_j = 125\text{ }^\circ\text{C}$

Fig. 24. Source current as a function of source-drain voltage; typical values

11. Package outline

DFN8080-8: plastic thermal enhanced small outline package; no leads; 8 terminals; body: 8 × 8 × 0.9 mm

SOT8074-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	k	L	y	u	v	w
max	1.0	0.05	0.203	1.05	8	7.04	8	3.3	2	0.9	1	0.6	0.1	0.1	0.1	0.05
nom	0.9	0.02	REF	1.00	BSC	6.94	BSC	3.2	BSC	BSC	REF	0.5				
min	0.8	0.00		0.92		6.84		3.1				0.4				

sot8074-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT8074-1		MO-229 compatible			23-03-03

Fig. 25. Package outline DFN8080-8 (SOT8074-1)

12. Soldering

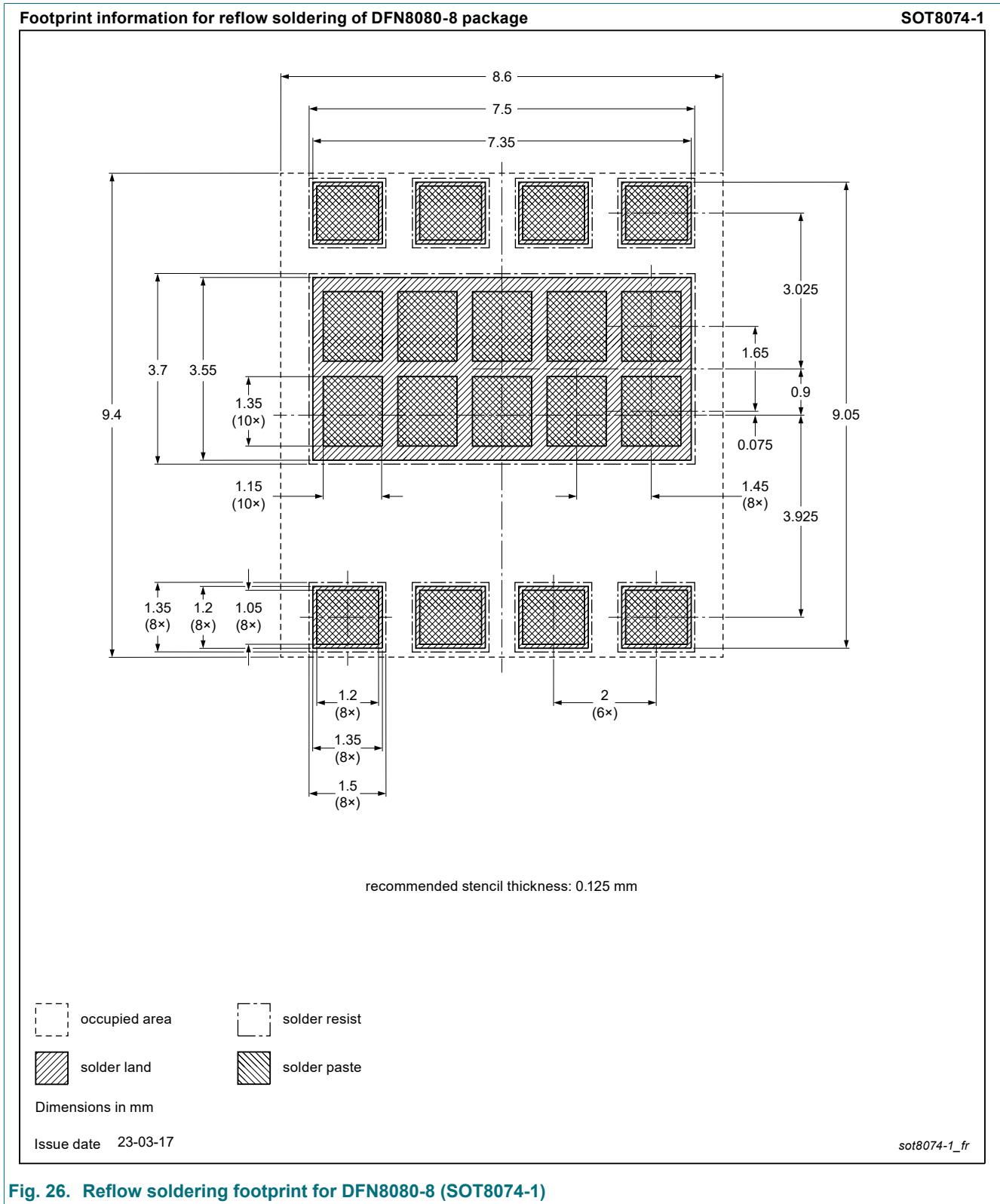


Fig. 26. Reflow soldering footprint for DFN8080-8 (SOT8074-1)

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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Contents

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	3
9. Thermal characteristics.....	4
10. Characteristics.....	5
11. Package outline.....	12
12. Soldering.....	13
13. Legal information.....	14

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